2007

9th Electronics Packaging Technology Conference

10 – 12 December 2007, Singapore

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PRINTED IN SINGAPORE

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IEEE Catalog Number	07EX1831	Print Version
	07EX1831C	CD-ROM Version
Library of Congress Number	2007927420	
ISBN	1-4244-1324-9	Print Version
	1-4244-1323-0	CD-ROM Version

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